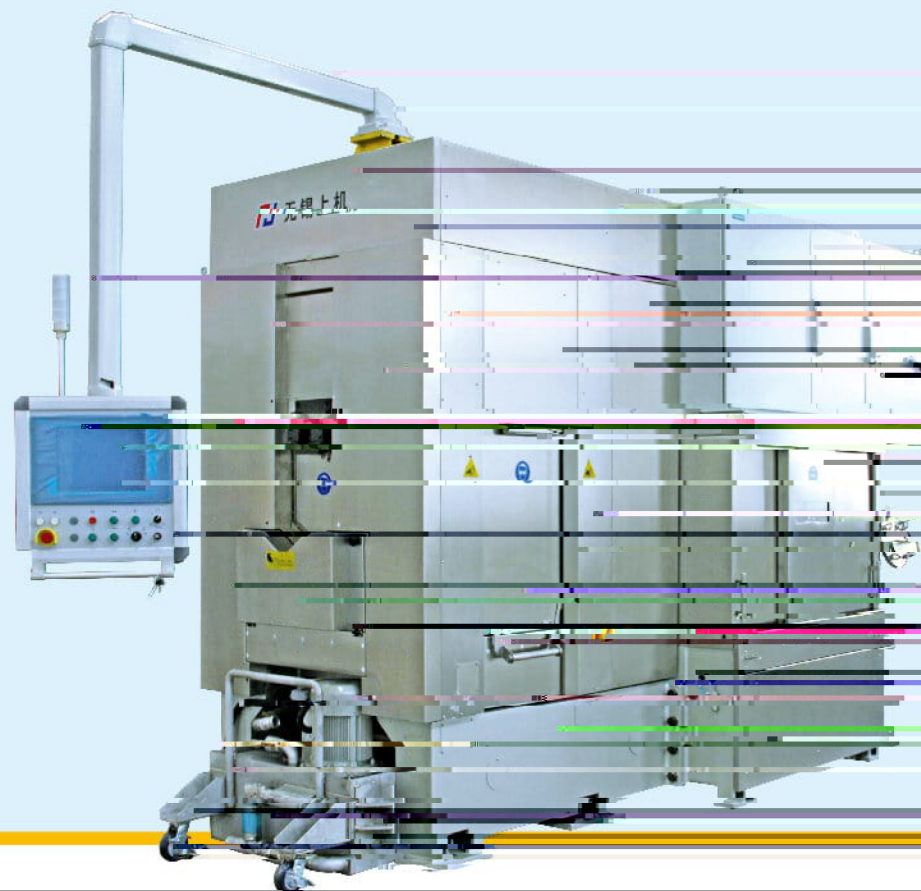


WSK060

蓝宝石切片机

WSK060 Sapphire Slicing Machine



技术规格参数 Specifications and Technical Parameters

规格 Specification	inches (max)
长度 Length	600mm
厚度 Thickness	>0.2mm

主要参数 Main Parameters

导轮直径 Guide wheel diameter	220mm
导轮轴距 Guide wheelbase	440mm
导轮长度 Guide wheel length	300mm
线速度 Wire speed	3000m/min
进给速率 Feeder rate	100mm-200mm/min
摇摆角度 Swinging angle	±12°
切割方向 Cutting direction	forward or reverse cutting / auto high cutting
导轮表面 Average wire wheels	220mm
冷却容量 Water cooling capacity	250L

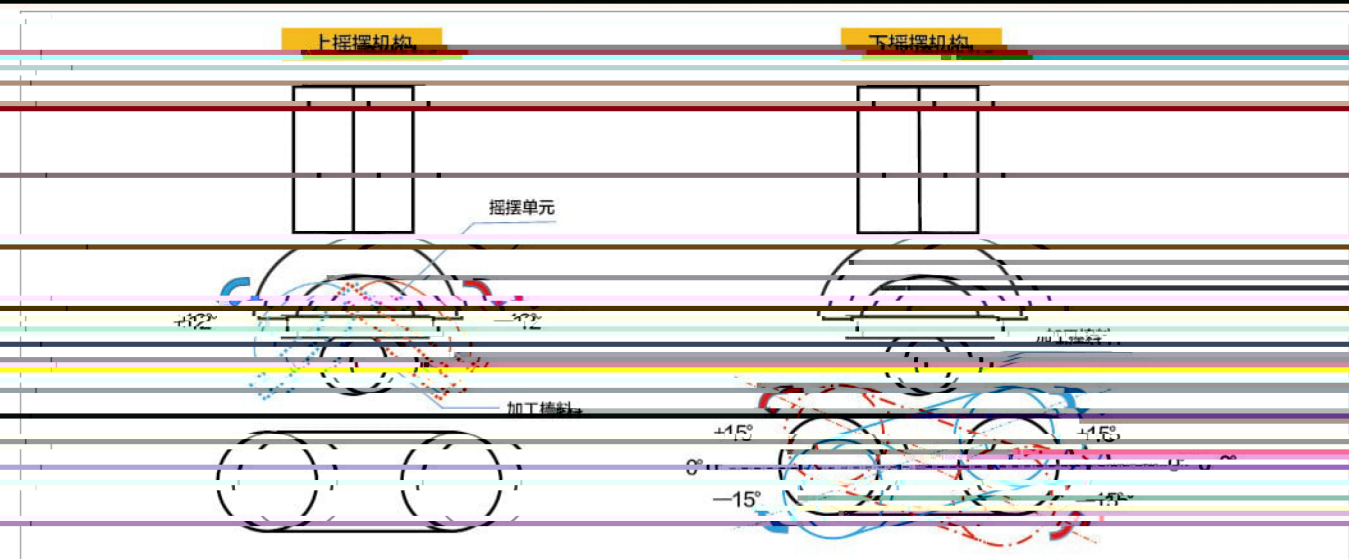
能源供给 power supply

电源电压 Power voltage	220V/380V, 50Hz, 3-phase
平均功率 Average power	35Kw
冷却水温度 Cooling water	10-25°C

外形尺寸 outline size

机床尺寸 (长×宽×高) Equipment size (L×W×H)	4600×2500×2100mm
机床重量 weight	≈ 12000kg

示意图 Sketch



设备用途与性能特征

- 本机用于自动切割长条，坚硬且易磨损材料，如蓝宝石、硅、锗、石英玻璃、陶瓷、蓝宝石晶体等。
- 机床所有电器元件均采用国际国内知名品牌，保证机床的稳定性。
- 采用西门子的控制技术的，一体化PC机，15"触摸屏。
- 电控柜配备独立温控系统，保证各控制元件正常工作。
- 设备具备摇摆功能，双支撑摇摆单元优化了金刚线切割蓝宝石的性能，缩短了切割时间，并提高了晶片的质量。
- 滑轮数量最少化设计（仅6个滑轮），减少刚线扭曲和疲劳。

Application and Features

- The machine is used for automatically cutting long, hard and wear-resistant materials using diamond tools to produce gemstones, crystals, glass, ceramics, sapphire crystals, etc.
- All electrical components apply international and domestic outstanding brands to ensure the stability of the machine.
- Apply integrated PC or SIEMENS simotion controlling system, 15" touch screen.
- The electric control cabinet is equipped with independent temperature control system to ensure the normal operation of each control component.
- The equipment features swinging function, and the dual-support swinging function unit optimizes the performance of diamond wire-cut sapphire, shortens the cutting time, and improves the wafer quality.
- Minimal design number of pulleys (only 6 pulleys) to reduce wire distortion and fatigue.